

ABSTRACT OF THE DISCLOSURE

A carrier structure comprises a carrier base which is not thermally deformable and a portion of which is also transparent to electromagnetic radiation. An adhesive layer is disposed on a surface of the carrier base. Semiconductor chips or other items adhere to the adhesive layer, which is cross-linked when it is desired to remove the chips. Once the chips have been removed, the adhesive layer may be removed from the carrier base. The carrier base can be re-used to transport and hold semiconductor chips after application of a new adhesive layer. A carrier frame may releasably support the carrier base.

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